# FlexVIA™-Plus Plasma System

#### **Features and Benefits**

- Efficient design, economical gas consumption and small footprint contribute to low cost of ownership
- Easy loading and versatile horizontal racks allow for processing of various flexible PCB panel sizes
- Single stage plasma process and capacity for up to 30, 20" x 32" panels per cycle, enabling a rate of 140-200 units per hour (UPH)
- Patented, industry-proven plasma technologies provide superior surface activation, etch back, and desmear process uniformity
- Temperature controlled electrodes ensures consistent process repeatability



#### **Efficient and Cost Effective**

Specifically designed for the processing of flexible PCB substrates, the FlexVIA<sup>™</sup>-Plus system from Nordson MARCH further extends the VIA<sup>™</sup> series technology platform into the field of flexible material application.

The FlexVIA-Plus system delivers superior uniformity and efficiency for applications such as surface treatment, etch back, and desmear. Uniform plasma treatment of both sides of the flex material surface area is possible, enabling rates of 140-200 units per hour (UPH).

The FlexVIA-Plus system's advanced horizontal electrode design, with integrated rack, provides optimum material alignment for industry leading plasma treatment uniformity. The dual-rack chamber accommodates up to 30, 20"x 24"panels in a single cycle.

Fully self-contained, the FlexVIA-Plus system maximizes process capacity and minimizes usage of valuable production floor/area. It features a space-saving, compact chassis with two easy-access, front-loading doors.

#### **Easy to Use**

The FlexVIA-Plus system makes it easy to load various sizes of flexible materials into the chamber via two, optimum height, front-loading doors. Convenient carts smoothly slide the racks in and out of the system. The loading racks include versatile slide out trays to accommodate many different flexible material sizes. The system is controlled by an intuitive touch screen GUI with a one-button start feature.

### **Innovation and Applications**

The FlexVIA-Plus system further builds on the success of the Nordson MARCH VIA series line of products (ProVIA<sup>™</sup>, MaxVIA<sup>™</sup>, and RollVIA<sup>™</sup> plasma systems) which incorporate innovative application-specific technology with over 25 years of experience in plasma treatment for the PCB industry.



## Specifications: FlexVIA<sup>™</sup>-Plus Plasma System

Enclosure Dimensions	W x D x H – Footprint	1890W x 1585D x 2285H mm
	<u> </u>	(74W x 62D x 90H in.)
	Net Weight	2070 kg (4564 lbs)
Chamber	Number of Available Cells	30
Electrodes RF Power	Configuration	Temperature Controlled Power-Power
	Working Area	508W x 830D mm; (20W x 32D in.)
	Standard Wattage	5 kW
	Optional Wattage	10 kW
	Frequency	40 kHz
Gas Control	Available Flow Volumes	500, 1000, 2000 or 5000 sccms
	Maximum Number of MFCs	5
Control	Interface	EPC with PC-Based Touch Screen Interface
Vacuum Pump Facilities	Standard Purged Pump Package	530 cfm
	Cooling Water Flow	9.5 slm
	N2 Pump Purge Flow	14 slm
	Power Supply	208 VAC, 50 A, 3-Phase + Ground; 50/60 Hz
	Process Gas Fitting Size & Type	6.35 mm (0.25 in.) Swagelok
	Process Gas Purity	CF4 = 99.97%; O2 = 99.996%; N2 = 99.99%;
	•	Ar = 99.999%; H2 = 99.999%
	Process Gas Pressure	1.03 bar (15 psig) min. to 1.7 bar (25 psig) max., regulated
	Purge Gas Fitting Size & Type	9.5 mm (0.375 in.) Swagelok Tube
	Purge Gas Purity	N2 = 99.99%
	Purge Gas Pressure	1.03 bar (15 psig) min. to 1.7 bar (25 psig) max., regulated
	Pneumatic Valves Fitting Size & Type	9.5 mm (0.375 in.) Swagelok
	Pneumatic Gas Purity	CDA, Oil Free, Dewpoint ≤7°C (45°F), Particulate Size <5 μm
	Pneumatic Gas Pressure	6.2 bar (90 psig) min. to 6.9 bar (100 psig) max., regulated
	Exhaust	NW 40 @ Utility Panel
Compliance	USA	EH&S/Ergonomics
	International	CE Marked
Ancillary Equipment	Gas Generators	Nitrogen, Hydrogen
		(requires Additional Non-Optional Hardware)
	Facilities	Chiller, Scrubber, Transformer

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